RELIABILITY REPORT

FOR

MAX6701SKA+

PLASTIC ENCAPSULATED DEVICES

February 4, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX6701SKA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX6701-MAX6708 microprocessor (µP) supervisory circuits reduce the complexity and components required to monitor power-supply functions in µP systems. These devices significantly improve system reliability and accuracy compared to separate ICs or discrete components. The MAX6701-MAX6708 family provides four functions: a reset output during power-up, power-down, and brownout conditions; an independent watchdog output that goes low if the watchdog input has not been toggled within 1.6s; a 0.62V threshold detector for power-fail warning; and an active-low manual reset input. The MAX6701-MAX6708 family offers several pinout options to accommodate a variety of multivoltage microprocessor supervision applications. The MAX6701(A)/MAX6702(A)/MAX6703(A) monitor three supply voltages (one fixed threshold and two adjustable) to drive a single reset output and include a manual reset input and a watchdog timer with an independent output. The MAX6704 monitors a single-supply voltage to drive complementary reset outputs and includes an independent adjustable power-fail-in/power-fail-out comparator, a manual reset input, and a reset-based watchdog timer. The MAX6705(A)/MAX6706(A)/MAX6707(A) monitor a single-supply voltage to drive a single reset output and include an independent adjustable power-fail-in/power-fail-out comparator, a manual reset input, and a watchdog timer with an independent output. The MAX6708 is the same as the MAX6704 but without the watchdog timer function. *See the Detailed Description for differences between non-A and A versions.*

II. Manufacturing Information

A. Description/Function:	Low-Voltage, SOT23, µP Supervisors with Power-Fail In/Out, Manual Reset, and Watchdog Timer
B. Process:	B8
C. Number of Device Transistors:	745
D. Fabrication Location:	California or Texas
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	January 27, 2001

III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0136
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	112*°C/W
K. Single Layer Theta Jc:	80°C/W

IV. Die Information

A. Dimensions:	62 X 24 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.71 \times 10^{-9}$

λ = 6.71 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The MS51-4 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX6701SKA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	160	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data